

DESCRIPTION

The MXN3388L uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. It can be used in a wide variety of applications. It is ESD protected.

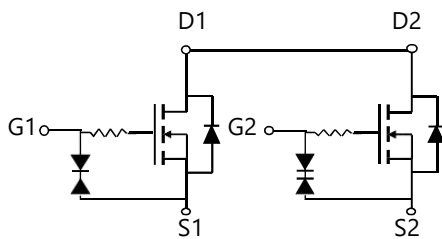
GENERAL FEATURES

- $V_{DS}=20V$, $I_D=8A$
 $R_{DS(ON)}(Typ.)=15.5m\Omega$ @ $V_{GS}=2.5V$
 $R_{DS(ON)}(Typ.)=10.6m\Omega$ @ $V_{GS}=3.8V$
 $R_{DS(ON)}(Typ.)=10m\Omega$ @ $V_{GS}=4.5V$
 ESD Rating: 2000V HBM
- High density cell design for ultra low R_{dson}
- Fully characterized Avalanche voltage and current

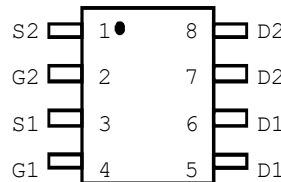
APPLICATION

- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply

PINOUT



Schematic diagram



Pin Assignment



DFN3X3-8L top view

ORDERING INFORMATION

Part Number	Storage Temperature	Package	Devices Per Reel
MXN3388L	-55°C to 150°C	DFN3X3-8L	5000

ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous	I_D	8	A
Drain Current-Continuous ($T_A=100^\circ C$)	$I_D(100^\circ C)$	6	A
Pulsed Drain Current ^(Note1)	I_{DM}	32	A
Maximum Power Dissipation	P_D	2.5	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$

THERMAL RESISTANCE

Thermal Resistance, Junction-to-Ambient ^(Note2)	$R_{\theta JA}$	50	$^\circ C/W$
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Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 2. Surface Mounted on FR4 Board, $t \leq 10$ sec.


ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
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Off Characteristics

Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	20	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20V, V_{GS}=0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	± 10	μA

On Characteristics (Note 3)

Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.45	0.75	1.2	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=2.5V, I_D=4A$	-	15.5	22	$m\Omega$
		$V_{GS}=3.8V, I_D=6A$	-	10.6	15	$m\Omega$
		$V_{GS}=4.5V, I_D=6A$	-	10	13.5	$m\Omega$
Forward Transconductance	g_{FS}	$V_{DS}=5V, I_D=8A$	-	15	-	S

Dynamic Characteristics (Note 4)

Input Capacitance	C_{iss}	$V_{DS}=15V, V_{GS}=0V,$ $F=1.0MHz$	-	735	-	pF
Output Capacitance	C_{oss}		-	83	-	pF
Reverse Transfer Capacitance (Note 4)	C_{rss}		-	81	-	pF

Switching Characteristics

Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=10V, I_D=1A$ $V_{GS}=5V, R_G=6\Omega$	-	7.2	-	nS
Turn-on Rise Time	t_r		-	36	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	45	-	nS
Turn-Off Fall Time	t_f		-	15	-	nS
Total Gate Charge	Q_g	$V_{DS}=10V, I_D=6A,$ $V_{GS}=4.5V$	-	11	-	nC
Gate-Source Charge	Q_{gs}		-	2.2	-	nC
Gate-Drain Charge	Q_{gd}		-	4.1	-	nC

Drain-Source Diode Characteristics

Diode Forward Voltage (Note 3)	V_{SD}	$V_{GS}=0V, I_S=1A$	-	-	1.2	V
Diode Forward Current (Note 2)	I_S		-	-	3.5	A

Note 2. Surface Mounted on FR4 Board, $t \leq 10$ sec.

Note 3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.

Note 4. Guaranteed by design, not subject to product.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 1. Switching Test Circuit

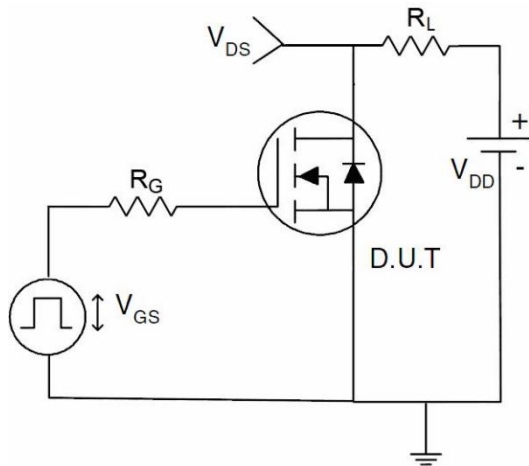


Figure 2. Switching Waveform

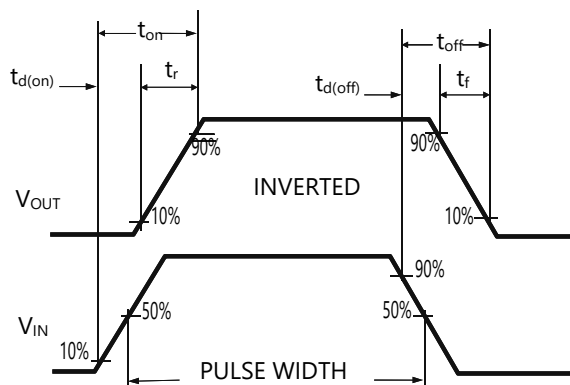


Figure 3. Power Dissipation

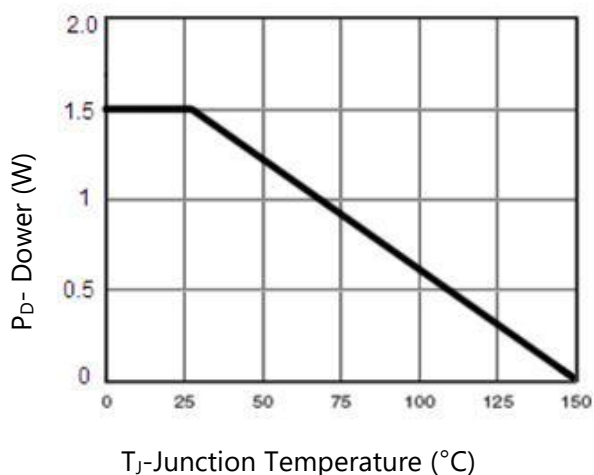


Figure 4. Drain Current

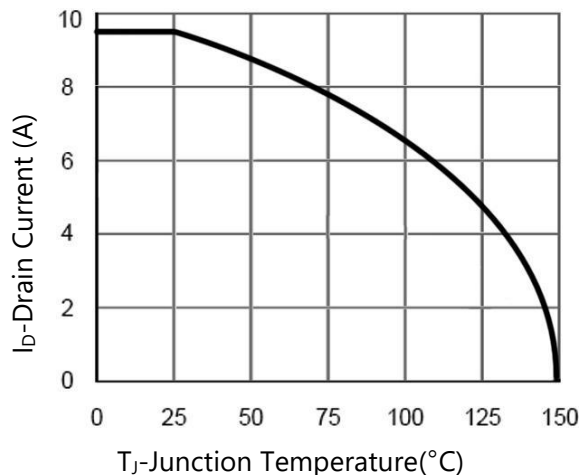


Figure 5. Output Characteristics

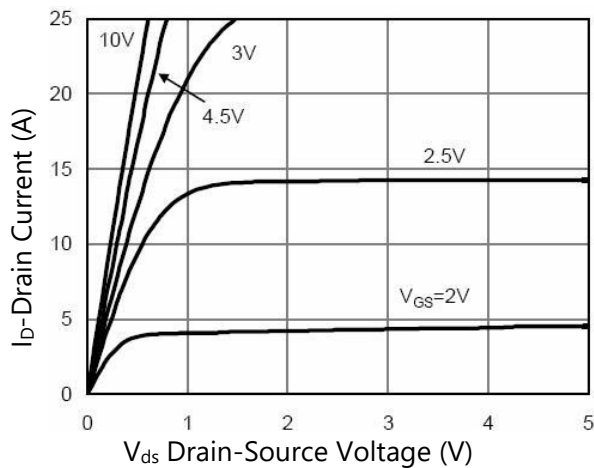
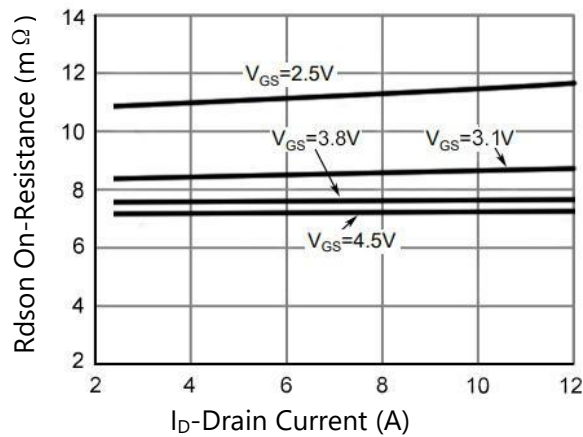


Figure 6. R_{dson} vs Drain Current



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7. Transfer Characteristics

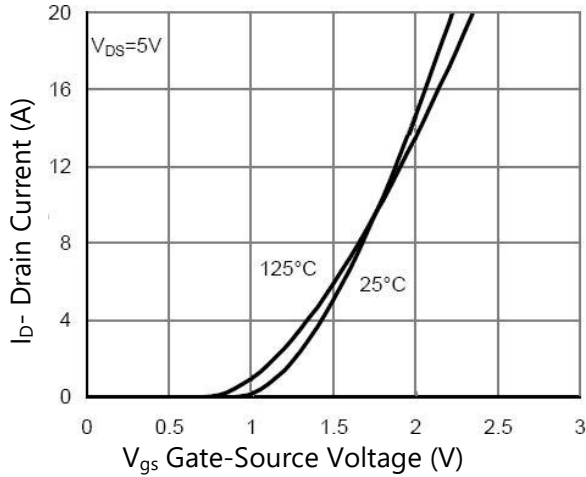


Figure 8. R_{dson} vs Junction Temperature

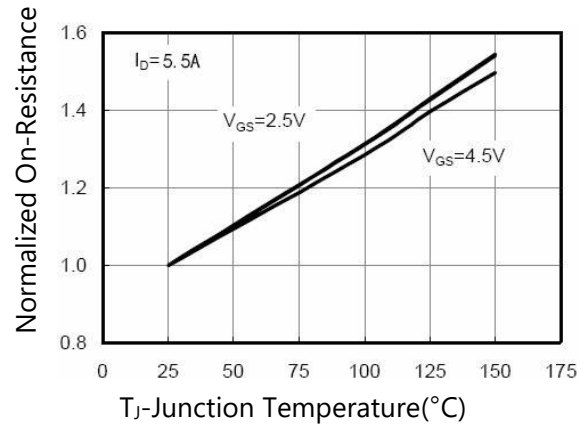


Figure 9. R_{dson} vs V_{GS}

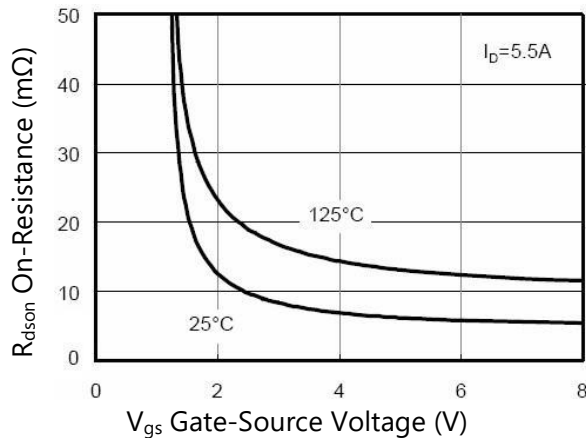


Figure 10. Capacitance vs V_{DS}

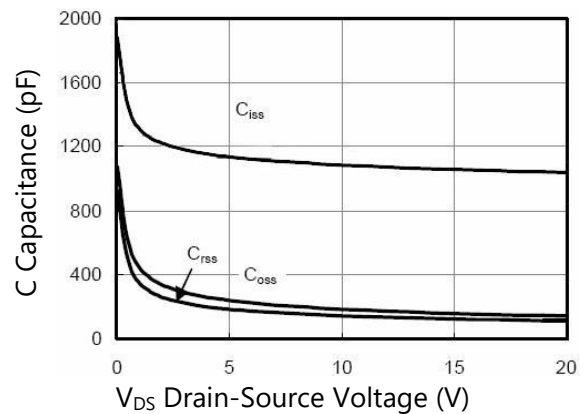


Figure 11. Gate Charge

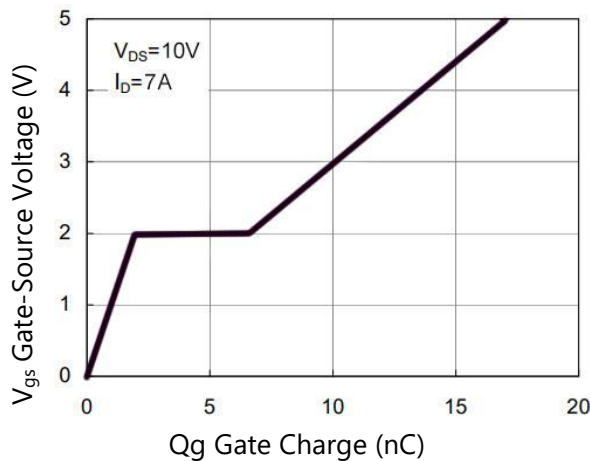
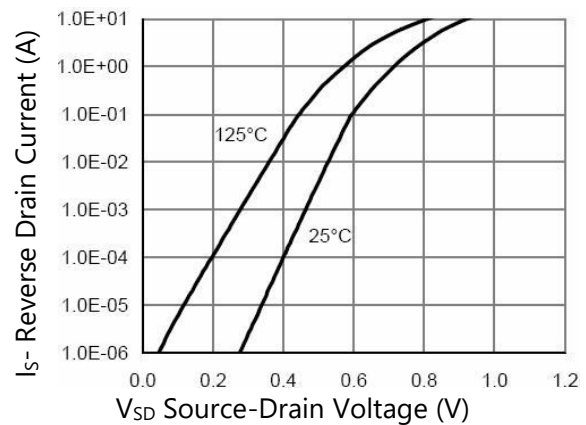


Figure 12. Source- Drain Diode Forward



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 13. Safe Operation Area

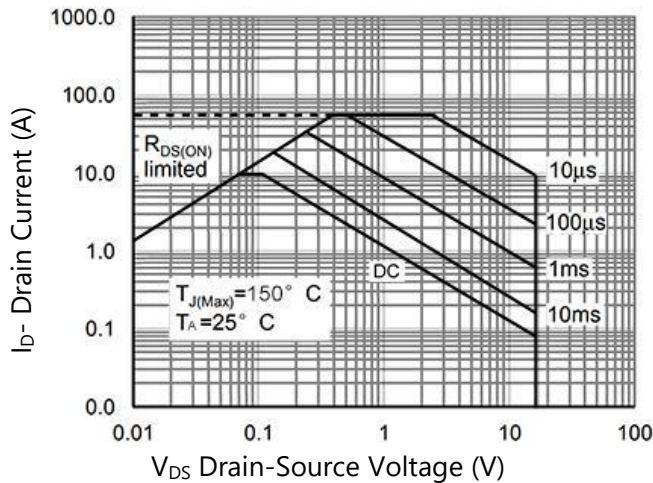
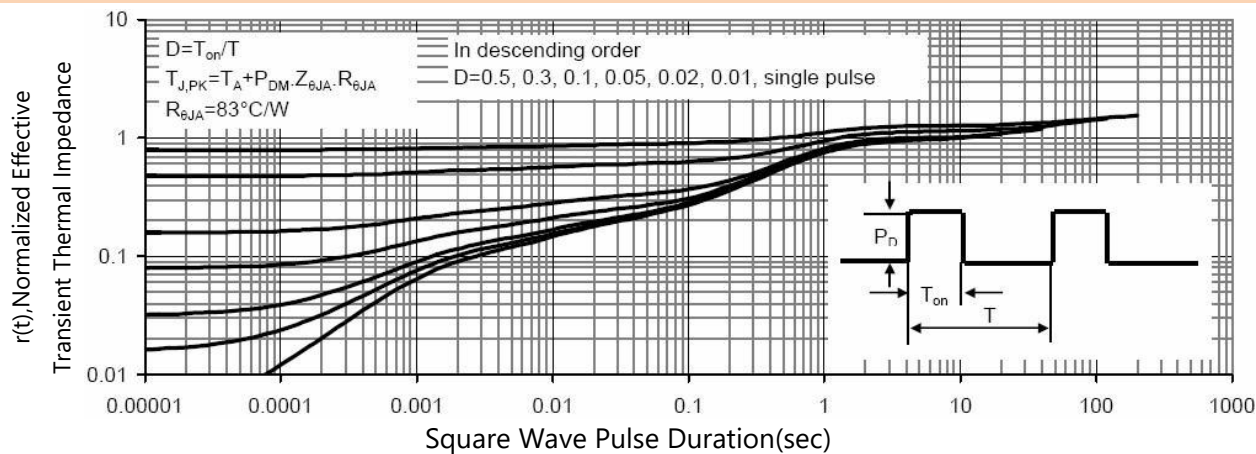
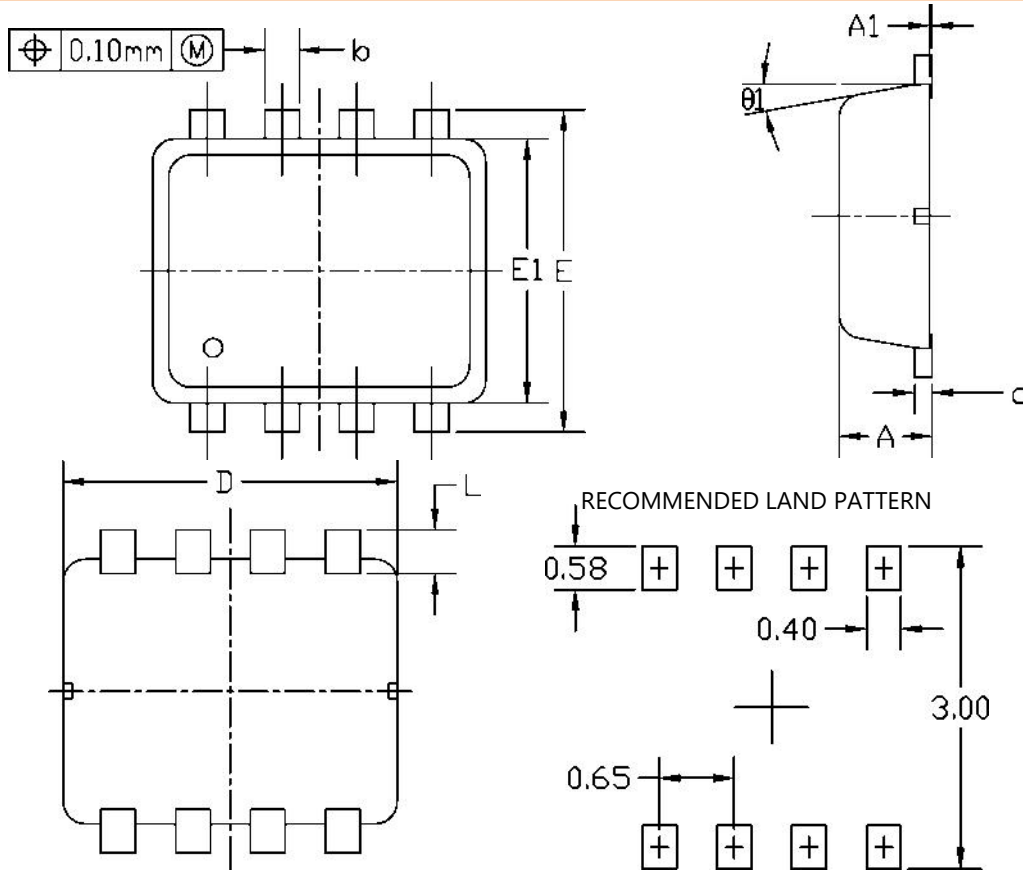


Figure 14. Normalized Maximum Transient Thermal Impedance



PACKAGE INFORMATION

DFN3X3-8L



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.80	0.90	0.028	0.031	0.035
A1	0.00	-	0.05	0.000	-	0.002
b	0.24	0.30	0.35	0.009	0.012	0.014
c	0.08	0.15	0.25	0.003	0.006	0.010
D	2.80	2.90	3.00	0.110	0.114	0.118
E	2.70	2.80	2.90	0.106	0.110	0.114
E1	2.20	2.30	2.40	0.0087	0.091	0.095
e	0.65 BSC			0.026 BSC		
L	0.20	0.38	0.45	0.008	0.015	0.018
01	0°	10°	12°	0°	10°	12°